



Product Change Notification / GBNG-20XTKS327

Date:

03-Nov-2020

Product Category:

8-bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3634.003 Final Notice: Qualification of MMT as an additional assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package with MSL 1 classification.

Affected CPNs:

[GBNG-20XTKS327_Affected_CPN_11032020.pdf](#)
[GBNG-20XTKS327_Affected_CPN_11032020.csv](#)

Notification Text:

PCN Status:

Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of MMT as an additional assembly site for selected Atmel products available in 32L VQFN (5x5x0.9mm) package with MSL 1 classification.

Pre Change:

For ATMEGA168PBxxx, ATMEGA48PBxxx and ATMEGA88PBxxx device families:

Assembled at ASCL assembly site with MSL 1 classification using Cu bond wire, EN-4900G die attach, 138x138 paddle size.

For ATMEGA1608xxx and ATMEGA808xxx device families:

Assembled at ASCL assembly site with MSL 3 classification using PdCu bond wire, EN-4900G die attach, 138x138 paddle size.

For ATMEGA328PBxxx device family: Assembled at ASCL assembly site with MSL 3 classification using CuPdCu bond wire, EN-4900G die attach, 138x138 paddle size

Post Change:

For ATMEGA168PBxxx, ATMEGA48PBxxx and ATMEGA88PBxxx device families:

Assembled at ASCL assembly site with MSL 1 classification using Cu bond wire, EN-4900G die attach, 138x138 paddle size.

Or

Assembled at MMT assembly site with MSL 1 classification using CuPdAu bond wire, 3280 die attach, 150x150 paddle size.

For ATMEGA1608xxx, ATMEGA808xxx and ATMEGA328PBxxx device families:

Assembled at MMT assembly site with MSL 1 classification using CuPdAu bond wire, 3280 die attach, 150x150 paddle size.

Pre and Post Change Summary: For ATMEGA168PBxxx, ATMEGA48PBxxx and ATMEGA88PBxxx device families:

		Pre Change		Post Change	
Assembly Site		ASE Group Chung-Li (ASCL)		ASE Group Chung-Li (ASCL)	Microchip Technology Thailand (Branch) (MMT)
MSL Classification		MSL 1		MSL 1	MSL1
Wire material		Cu		Cu	CuPdAu
Die attach material		EN-4900G		EN-4900G	3280
Molding compound material		G700		G700	G700
Lead frame	Material	C194		C194	C194
	Paddle size	138 x138		138 x138	150x150
	Design	Please see attached Pre and Post Change summary.			

For ATMEGA1608xxx, ATMEGA808xxx and ATMEGA328PBxxx device families:

		Pre Change		Post Change	
Assembly Site		ASE Group Chung-Li (ASCL)		Microchip Technology Thailand (Branch) (MMT)	
MSL Classification		MSL 3		MSL1	
Wire material		PdCu ^{Note 1}	CuPdAu ^{Note 2}	CuPdAu	
Die attach material		EN-4900G		3280	
Molding compound material		G700		G700	
Lead frame	Material	C194		C194	
	Paddle size	138 x138		150x150	
	Design	Please see attached Pre and Post Change summary.			

Note 1: Applicable with ATMEGA1608xxx and ATMEGA808xxx device families.

Note 2: Applicable with ATMEGA328PBxxx device family.

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve productivity and on-time delivery performance by qualify MMT as an additional assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date: November 15, 2020 (date code: 2047)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	November 2020				
Workweek	45	46	47	48	49
Qual Report Availability	X				
Final PCN Issue Date	X				
Estimated Implementation Date			X		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:**November 3, 2020:** Issued final notification. Attached the Qualification Report. Provided estimated first ship date to be on November 15, 2020.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:[PCN_GBNG-20XTKS327_Pre and Post Change Summary.pdf](#)[PCN_GBNG-20XTKS327_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

ATMEGA168PB-MU
ATMEGA168PB-MN
ATMEGA168PB-MNR
ATMEGA168PB-MUR
ATMEGA88PB-MU
ATMEGA48PB-MU
ATMEGA88PB-MN
ATMEGA48PB-MN
ATMEGA88PB-MNR
ATMEGA48PB-MNR
ATMEGA88PB-MUR
ATMEGA48PB-MUR
ATMEGA88PB-MURB75
ATMEGA808-MF
ATMEGA1608-MF
ATMEGA1608-MU
ATMEGA808-MU
ATMEGA1608-MUR
ATMEGA808-MUR
ATMEGA1608-MFR
ATMEGA808-MFR
ATMEGA328PB-MU
ATMEGA328PB-MN
ATMEGA328PB-MNR
ATMEGA328PB-MUR